



iconnexion

BUILT FOR DEFENCE —

READY FOR EVERY MISSION

iConnexion is a technical distributor supporting engineers with component selection, design-in, integration and supply continuity for mission-critical electronics. From concept through production, we help reduce technical and supply-chain risk across demanding defence programmes.

OUR VALUE FLOW — ENGINEERING SUPPORT AT EVERY STAGE



Understand
Application Needs



Component Selection &
Value Engineering



Samples &
Design-In Support



Custom Cable &
Value-Added Solutions



Technical Validation
& Documentation



Production &
Supply Continuity

MORE THAN DISTRIBUTION.

ENGINEERING SUPPORT FROM DESIGN-IN TO PRODUCTION.

ABOUT ICONNEXION

Since 2007, iConnexion has supported OEM, ODM and EMS customers across APAC with electronic components and value-added services. For defence and high-reliability programmes, our approach combines application-focused component selection, technical support and supply continuity.

Our defence-focused portfolio spans interconnect, RF and wireless, power, passives, thermal management, sensors, semiconductors and supporting technologies. From design-in through production, we work with engineering and procurement teams to identify suitable solutions, reduce risk and support long-term availability.

**20 YEARS**
EXPERTISE OF
Since 2007


Headquartered
in Singapore


Broad Coverage
Across APAC

**10,000+ sq ft**
Warehouse
Storage
Capacity

**12**
APAC Sales & Support
Locations

**Awarded
Harwin APAC**
Distributor of the Year
2025/26

PRODUCT CATEGORIES

 Antennas	 Buzzer/ Speaker	 Connectors	 Discrete Components	 Electromechanical
 Embedded Solutions	 EV Charging Gun	 PCB/Flex PCB	 Passives	 Power Electronics
 RF & Wireless	 Semiconductors	 Sensors	 Thermal Management	

OUR BRAND PARTNERS









CONTENTS

01

About iConnexion

02

Why Engineers Choose iConnexion

03

Applications We Support

04

Harwin HRi

05

Harwin HRi Cable Assembly

06

Harwin BBi & Harwin Asia

07

Harwin Asia Antenna

08

Harwin Design Support

09

LS Materials

10

Hotron

11

Fujipoly

12

CAP-XX

13

Tetek

14

Taitien

15

Silvertel & IEH

16

DACO Semiconductor

17

INPAQ & Matsuo

18

Nitsuko & Soshin

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WHY ENGINEERS CHOOSE ICONNEXION

We help engineers select, integrate, evaluate and customise mission-critical components — supporting projects from design-in through production.



APPLICATION-FOCUSED

We start with the application requirements — performance, reliability, SWaP, environmental constraints and lifecycle needs — then help identify suitable component solutions.



TECHNICAL EXPERTISE

Our engineers combine product knowledge with application insight to simplify component decisions, support technical evaluation and keep development moving.



DESIGN-IN SUPPORT

From concept through prototype to production, we support component evaluation, samples, technical documentation and hands-on design-in guidance to reduce integration risk.



VALIDATION & DOCUMENTATION

We support qualification activities with available datasheets, drawings, traceability and test documentation to support engineering review and programme requirements.



VALUE ENGINEERING & CUSTOMISATION

We evaluate alternative component solutions across performance, cost and supply considerations, and support kitting, cable/harness assemblies, modified configurations and custom solutions where required.



SUPPLY CONTINUITY

We help manage lifecycle and supply risk through availability planning, obsolescence visibility and proactive sourcing strategies to support long-term programmes.



APPLICATIONS WE SUPPORT



01
PRECISION-GUIDED
SYSTEMS



02
SATELLITES



03
SOLDIER & TACTICAL
SYSTEMS



04
LAUNCH
SYSTEMS



05
UAVs
(UNCREWED AERIAL
VEHICLES)













06
GROUND CONTROL &
RADAR SYSTEMS



07
LAND DEFENCE
SYSTEMS



08
SMALL SATELLITES /
CUBESATS



09
NAVAL &
MARITIME SYSTEMS



10
ROCKET
SYSTEMS











YOUR TECHNICAL DISTRIBUTION PARTNER



iConnexion supports your engineering team beyond component supply through application insight, value engineering, sampling and evaluation, custom solutions, and sustained support across the product lifecycle.



TECHNICAL
INSIGHT



VALUE
ENGINEERING



SAMPLING &
EVALUATION



CUSTOM
SOLUTIONS



SUSTAINED
SUPPORT

ENGINEERING SUPPORT. DEPENDABLE SUPPLY. BUILT AROUND YOUR MISSION.

HARWIN

HARWIN HRi —
RUGGED INTERCONNECT SOLUTIONS

Select the Harwin HRi family to match your electrical, mechanical and environmental requirements. These high-reliability interconnects are engineered for demanding applications where shock, vibration, temperature and secure mating matter.



HRi
RANGE



GECKO



High-Reliability Signal Interconnects

-  **Best for:** Compact, high-reliability signal connections
-  **Key strength:** 1.25 mm pitch, 2 A per contact and a 4-finger beryllium-copper contact system engineered to maintain connection through shock and vibration.

Current	Pitch	Temperature
2 A/contact (all loaded)	1.25 mm	-65°C to +150°C

GECKO-MT



Mixed Power + Signal in a Compact Footprint

-  **Best for:** SWaP-C-constrained systems requiring power and signal in one connector
-  **Key strength:** Up to 10 A power contacts plus 2 A signal contacts, with 1.25 mm signal pitch and rugged screw-lock / backshell options.

Current	Pitch	Temperature
10 A power / 2 A signal	1.25 mm	-65°C to +150°C

DATAMATE



Proven High-Reliability Signal Interconnects

-  **Best for:** Signal interconnects requiring secure mating and a broad configuration range
-  **Key strength:** 2.00 mm signal pitch, 3 A per signal contact, 4-finger contacts and jackscrew, latch or quick-mating options.

Current	Pitch	Temperature
3 A signal	2.00 mm	-55°C to +125°C

DATAMATE MIX-TEK



Mixed Signal, Power & Coax

-  **Best for:** Combining signal, high-current power and coaxial contacts in one connector
-  **Key strength:** Datamate Mix-Tek supports 3 A signal contacts, high-power contacts up to 40 A and 50 Ω coaxial options within mixed layouts.

Current	Pitch	Temperature
40 A power / 3 A signal	2.00 mm signal / 4.00 mm power-coax	-55°C to +125°C

M300



Compact High-Reliability Power

-  **Best for:** Compact power connections exposed to shock, vibration and elevated temperature
-  **Key strength:** 10 A per contact, 3.00 mm pitch, 4-finger contact design and operation up to +175°C.

Current	Pitch	Temperature
10 A/contact	3.00 mm	-65°C to +175°C

KONA



High-Current Power Interconnects

-  **Best for:** High-current power distribution in harsh environments
-  **Key strength:** 60 A per contact with 8.50 mm pitch, secure screw-locking and performance tested to 20 g vibration and 100 g shock.

Current	Pitch	Temperature
60 A/contact	8.50 mm	-65°C to +150°C

CUSTOM CABLE ASSEMBLY CAPABILITIES

ENGINEERED TO YOUR APPLICATION. BUILT TO CONTROLLED DRAWINGS.



iConnexion supports Harwin HRi cable assemblies from configuration and drawing development through custom build, inspection and production support.



SHIELDING & EMC CONTROL

Shielding, braid termination and strain-relief options matched to signal integrity and environmental requirements.



CUSTOM LABELLING

Application-specific cable identification for assembly, installation, maintenance and traceability.



TWISTED PAIR & CONTROLLED WIRING

Twisted-pair construction and controlled cable routing to support EMI control and signal integrity.



CABLE & WIRE SELECTION

Application-specific wire gauge, insulation, shielding, temperature and flexibility requirements.



BACKPOTTING & STRAIN RELIEF

Backpotting options for connector support, strain relief and environmental protection where the connector design permits.



DOCUMENTATION & TRACEABILITY

Controlled drawings, BOM/build records, inspection/test records and traceability as required by the programme.

CONTROLLED WORKMANSHIP

Assembly and inspection to approved drawings and defined workmanship criteria.

APPLICATION-SPECIFIC ENGINEERING

Cable construction and materials tailored to the electrical, mechanical and environmental requirements.

INSPECTION & TEST

Build verification to the drawing and agreed electrical and inspection requirements.

END-TO-END SUPPORT

Support from configuration and prototype through documentation, production and supply.

BBi CONNECTOR FAMILIES

A broad interconnect portfolio for compact, high-density and application-specific electronics — combining Harwin BBi products with Harwin Asia localised solutions.



FLECTO



Floating Board-to-Board Connectors

Fine-pitch, high-pin-count floating connectors designed to absorb positional misalignment in X, Y and Z axes, reducing mechanical stress in multi-connector PCB assemblies.

Applications

- Avionics electronics
- Rugged embedded systems

KONTROL



Rugged 1.27 mm PCB & Cable Interconnects

Fully shrouded, polarised 1.27 mm connectors with board-to-board and cable-to-board options for reliable, space-efficient interconnection.

Applications

- Mission electronics
- C4ISR / embedded systems

ARCHER



Compact High-Density PCB Interconnects

0.5 mm, 0.8 mm and 1.27 mm connector options for high-density board-to-board and cable-to-board designs, including high-speed variants.

Applications

- Avionics electronics
- Embedded computing



 USB 3.2 TYPE-C RECEPTACLE (IPX8) High-speed USB Type-C interconnects with IPX8 waterproof variants; USB 3.2 versions support up to 20 Gbit/s and 5 A VBUS.	 SMT SPACER Surface-mount PCB spacers and bosses for controlled board spacing, mounting and mechanical support.	 RF CABLE & ADAPTER SOLUTIONS 50 Ω RF cable and adapter options for compact signal routing and RF interconnection.	 SMT EMI CONTACT FINGER Surface-mount spring contacts for grounding, shielding and EMI control in compact electronic assemblies.	 SIGNALCORE IDC CONNECTOR Compact IDC-based board and cable interconnect solutions for dense electronic assemblies.	 2.4/5 GHz MID SMT ANTENNA Compact embedded antenna option for 2.4 GHz and 5 GHz wireless applications.	 FINE-PITCH FPC CONNECTOR Compact FPC interconnects, including 0.5 mm-pitch, 1.2 mm-high, right-angle SMT variants.
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ANTENNA SOLUTIONS

CONNECTIVITY FOR COMMUNICATION, POSITIONING & TELEMETRY

A broad antenna portfolio supporting LTE/5G, Wi-Fi, GNSS and ISM connectivity across embedded communications, positioning and telemetry systems for compact electronic platforms.



GOOSENECK OMNIDIRECTIONAL ANTENNA

- Heavy-duty IP67 design
- 900 MHz, 1.35 GHz & 2.4 GHz
- Tactical & UAV communications



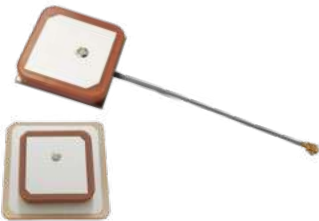
MULTIHUB 5-IN-1 & 7-IN-1 ANTENNAS

- LTE/5G, Wi-Fi & GPS connectivity
- Reliable communication & tracking
- IP67 rugged design
- Screw or adhesive mounting



LTE/5G & 2.4/5 GHz UAV ANTENNAS

- Compact omnidirectional design
- LTE/5G & 2.4/5 GHz support
- Reliable UAV communication
- Ideal for non-tactical UAVs



GPS/GNSS ANTENNAS FOR TRACKING & POSITIONING

- Passive & active RHCP options
- GPS & GLONASS support
- 30 dB active amplification
- Vehicle, asset & UAV tracking



WI-FI ANTENNAS FOR MILITARY COMMUNICATION

- Dipole & 4x4 MIMO options
- Stable plug-and-play performance
- Four antennas in one assembly
- Military Wi-Fi applications

HARWIN DESIGN SUPPORT FOR DEFENCE PROGRAMMES

From concept through production, iConnexion combines application engineering with Harwin HRI interconnect technology to support demanding defence programmes.



SPACE & SATELLITES

Lightweight, high-reliability interconnects for payload electronics, avionics, communications and control systems.



UAV & UNCREWED SYSTEMS

Compact, vibration-resistant interconnects for flight control, sensors, payloads, datalinks and power systems.



SOLDIER & TACTICAL SYSTEMS

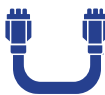
Rugged interconnects for radios, wearable electronics, batteries and portable mission systems.



NAVAL & LAND DEFENCE

Secure interconnects engineered for shock, vibration, temperature and demanding field environments.

HOW iCONNEXION ADDS VALUE



FAMILY SELECTION

Match the HRI family and configuration to electrical, mechanical, environmental and space requirements.



VALUE ENGINEERING

Evaluate alternatives against form, fit, function, performance, lifecycle, cost and qualification requirements.



SAMPLING & PROTOTYPES

Support early evaluation with samples and prototype quantities to keep design activity moving.



CUSTOM CABLE INTEGRATION

Support cable assembly configuration, drawing development and application-specific integration.



DOCUMENTATION SUPPORT

Provide access to drawings, datasheets, CAD models, test reports and supporting technical documentation.



DESIGN-IN FOLLOW-UP

Maintain technical follow-up through design review, validation, qualification activities and production ramp-up.

ENERGY STORAGE FOR DEFENCE ELECTRONICS

PEAK POWER. FAST RESPONSE. MISSION-READY.

LS Materials ultracapacitors provide high-power, rapid charge/discharge energy storage for peak-power support, backup, ride-through and transient-load management. iConnexion helps match cell or module configuration to the DC bus, load profile, duty cycle and operating environment.



VEHICLE ELECTRIFICATION & HV POWER

FROM CHARGING INTERFACE TO ON-VEHICLE POWER DISTRIBUTION

Hotron brings over 30 years of cable and interconnect expertise to EV charging, high-voltage vehicle wiring and energy-storage systems. iConnexion supports the evaluation and integration of these solutions for defence and electrified vehicle applications.



3.0 V ULTRACAPACITOR CELLS

- 3.0 V options from compact radial cells to large cylindrical formats.
- 60 mm cylindrical series available up to 3400 F.
- Low-ESR construction for high-power and peak-current applications.



BACKUP / RIDE-THROUGH

Supports short-duration backup, controlled shutdown, memory/RTC retention and transient load support when correctly sized.



16.2 V / 500 F ULTRACAPACITOR MODULE

- Rated 16.2 V, 500 F
- Max. DC ESR: 1.5 mΩ
- Max. continuous current: 200 A



ACTUATOR / TRANSIENT SUPPORT

High-power buffering for short-duration loads such as actuators, transmission bursts and other pulse-power events.



32.4 V / 250 F ULTRACAPACITOR MODULE

- Rated 32.4 V, 250 F
- Max. DC ESR: 3.3 mΩ
- Max. continuous current: 150 A



DC-BUS / LOAD BUFFERING

Supports peak-load shaving, ride-through and transient stabilisation in higher-voltage DC systems.



51.3 V / 166 F ULTRACAPACITOR MODULE

- Rated 51.3 V, 166 F
- Max. DC ESR: 5.0 mΩ
- Max. continuous current: 100 A



48 V-CLASS ENERGY BUFFERING

Suitable for energy buffering and DC-bus support in 48 V-class architectures when system voltage limits and controls are properly engineered.



AC EV CHARGING CONNECTORS

TYPE 1 / TYPE 2 / NACS

- 250 / 480 VAC, up to 70 A single-phase / 63 A three-phase
- ≥10,000 mating cycles
- IEC 62196-related configurations with multiple cable options



DC HIGH-VOLTAGE CHARGING CABLES

HIGH-POWER DC POWER TRANSFER

- 600 / 1,000 V operating voltage
- -40°C to +90°C temperature range
- Stranded copper conductor with XLPE insulation and TPU jacket



ON-VEHICLE HIGH-VOLTAGE CABLES

ELECTRIFIED VEHICLE POWER DISTRIBUTION

- ISO 19642-5 / ISO 19642-9 capability
- Supports battery, inverter, DC-DC and electric-drive interconnections
- Designed for high-voltage vehicle power distribution



ENERGY-STORAGE CABLE SOLUTIONS

BATTERY & HIGH-CURRENT INTERCONNECTION

- UL 11627 energy-storage cable capability
- Supports high-current DC and battery interconnections
- Suitable for energy-storage, auxiliary power and charging systems



POTENTIAL DEFENCE APPLICATIONS



Power Backup & Ride-Through



Radar / EO-IR Systems



Communications Infrastructure



Actuation & Transient Loads



Vehicle Power Management



Mission Electronics

THERMAL MANAGEMENT EXPERTISE

THERMAL INTERFACE MATERIALS FOR DENSE, RUGGED ELECTRONICS

Fujipoly SARCON® thermal interface materials improve the conductive heat path between heat-generating components and cooling surfaces. iConnexion supports material selection around thermal conductivity, gap size and tolerance, compression force, electrical isolation, silicone / non-silicone requirements and the assembly process.



ULTRA-THIN SUPERCAPACITOR SOLUTIONS

PULSE POWER. COMPACT ENERGY STORAGE. FAST RESPONSE.

CAP-XX prismatic supercapacitors combine low ESR, high capacitance and thin form factors for peak-current, backup and energy-buffering functions in space-constrained electronics. CAP-XX also offers lithium-ion hybrid capacitors where longer-duration energy storage and lower self-discharge are required.



STANDARD GAP FILLER PADS

Conformable sheet materials for filling component-to-heat-sink gaps while supporting thermal transfer and electrical isolation. SARCON standard-performance grades span approximately 1.4–4.5 W/m·K.



GENERAL GAP FILLING

Useful where compliance, electrical isolation and controlled compression are required.



FORM-IN-PLACE GAP FILLERS

Dispensable, form-stable materials for complex geometry and larger or irregular gaps. Current SARCON form-in-place grades span approximately 2.1–7.0 W/m·K.



IRREGULAR GEOMETRY

Helps fill uneven gaps with low compression force; selected grades also provide vibration absorption.



HIGH-PERFORMANCE GAP FILLER PADS

Highly conformable sheet materials for higher heat-flux designs. Current SARCON high-performance grades span approximately 8–13 W/m·K.



HIGHER HEAT FLUX

For designs that need increased thermal conductivity while retaining gap-filling compliance.



PUTTY-TYPE GAP FILLERS

Extremely compressible thermal interface materials designed to conform to uneven mating surfaces with very low compression force. Current SARCON putty grades span approximately 2.5–13 W/m·K.



LOW COMPRESSION FORCE

Useful where board or component stress must be controlled across irregular gaps.



CARBON-FIBRE GAP FILLERS

Carbon fibres oriented through the thickness provide very high through-plane thermal conductivity. CF210A is rated at 21 W/m·K and CF400A at 40 W/m·K according to ASTM D5470.



ULTRA-HIGH THERMAL CONDUCTIVITY

For demanding wide-gap thermal paths where very high conductivity is required; electrical characteristics must be checked for the application.

DMH ULTRA-THIN PRISMATIC SUPERCAPACITOR



Representative DMHA device
4.5 V, 40 mF, 600 mΩ DC ESR in an ultra-thin prismatic format down to 0.4 mm thick.



Extreme Space Constraints
For short-duration pulse or backup functions where thickness is the dominant packaging constraint.

DMF LOW-ESR PRISMATIC SUPERCAPACITOR



High-Power 5.5 V DMF Supercapacitors

DMF series combines low ESR with useful energy density; 5.5 V variants include 470 mF / 50 mΩ and 200 mF / 105 mΩ devices.



Peak-Current Support

Supports burst loads, radio transmissions, actuators and short ride-through in compact electronics.

DMV 3.0 V PRISMATIC SUPERCAPACITOR



Representative DMV device
3.0 V, 700 mF, 150 mΩ DC ESR in a compact 21 × 14 × 2.2 mm format.



Compact Energy Buffer
Useful where a single-cell 3 V rail needs pulse support or short-duration backup.

LY-H LITHIUM-ION HYBRID CAPACITOR



3.8 V High-Temperature Lithium Hybrid Capacitors

Lithium-ion hybrid capacitors for industrial-temperature applications combine supercapacitor response with greater energy storage. LY-H devices are rated 3.8 V and support operation up to 85°C when operated at 3.5 V.



Peak-Current Support

For applications needing more stored energy, longer standby time, and lower self-discharge than a conventional supercapacitor.

BUILT FOR COMPACT, HIGH-DEMAND ELECTRONICS



UNMANNED SYSTEMS



TACTICAL COMMUNICATIONS



COMPACT MISSION DEVICES



ENERGY BUFFERING



CUSTOM & RUGGED CABLE ASSEMBLY SOLUTIONS

ENGINEERED TO SPECIFICATION.
QUALIFIED FOR THE APPLICATION.

TOTEK manufactures custom cable assemblies across automotive, telecommunications, new-energy and industrial applications, including FAKRA, waterproof, M12, energy-storage and MC4 solutions. For defence programmes, iConnexion evaluates suitable constructions against the required electrical, mechanical, environmental and documentation requirements before design-in.



50 Ω FAKRA CABLE ASSEMBLIES

A–Z coding options for coaxial links used with antennas, GNSS, cameras and sensors. TOTEK connector data lists DC–6 GHz performance, -40°C to $+105^{\circ}\text{C}$ operation and optional IPX7 / IPX9K locked-condition variants.



IP67/IP68 CUSTOM CABLE ASSEMBLIES

Customised waterproof assemblies are available across multiple connector families, with overmoulding, cable, length and endpoint options selected to suit the application.



M12 INDUSTRIAL CABLE ASSEMBLIES

M12 A-code assemblies are available in multiple pole counts with shield options and IP67/IP68 locked-condition protection.



ENERGY-STORAGE / BATTERY CABLE ASSEMBLIES

TOTEK offers energy-storage cable assemblies including M23 / M25 battery-charging, mixed power-and-signal and high-current cable configurations.



MC4 FEMALE STRAIGHT CABLE ASSEMBLY

Published example: 30 A, 1000 V, -40°C to $+80^{\circ}\text{C}$, optional IP67/IP68 protection in the locked condition, with 16–20 AWG cable options.

BUILT FOR APPLICATION-SPECIFIC INTEGRATION



CUSTOM CONFIGURATION

Connector, cable, length, pinout, overmoulding and labelling matched to the drawing and requirements.



ENVIRONMENTAL OPTIONS

Waterproof, overmoulded and ruggedised constructions are available across selected product families.



SIGNAL, RF & POWER

Portfolio spans coaxial, data, sensor/control and high-current power cable assemblies.



QUALITY & VERIFICATION

Inspection and electrical / environmental verification should be defined against the agreed drawing and programme requirements.



TIMING & FREQUENCY CONTROL

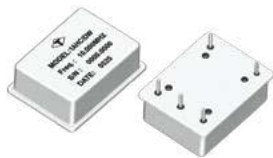
PRECISION TIMING FOR SYNCHRONISED
& DYNAMIC SYSTEMS.

Taitien provides TCXO, OCXO and GNSS-disciplined timing solutions for applications requiring frequency stability, low phase noise and resilience to vibration. iConnexion supports device selection around frequency, phase noise, g-sensitivity, power and environmental requirements.



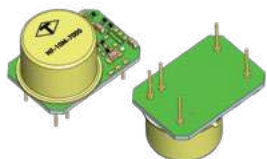
GNSS-DISCIPLINED OSCILLATOR (GNSSDO)

- DT-5151 example: 5 / 10 MHz disciplined output.
- GPS-disciplined 1PPS <30 ns; 24-hour holdover <1.5 μs .
- Timing reference for SATCOM, synchronisation and resilient-PNT architectures.



ULTRA-LOW-G-SENSITIVITY OCXO

- NI-100M-6700 example: 100 MHz, <0.05 ppb/g acceleration sensitivity.
- ± 100 ppb frequency stability over -40°C to $+85^{\circ}\text{C}$.
- Low-phase-noise reference for radar, GNSS and high-vibration RF systems.



ULTRA-LOW-POWER OCXO

- NP-100M-7000 example: 100 MHz with 120 mW typical steady-state power.
- ± 100 ppb frequency stability over -40°C to $+85^{\circ}\text{C}$.
- For portable communications, GNSS receivers and power-constrained precision timing.



COMPACT LOW-G-SENSITIVITY TCXO

- TP series: $3.2 \times 2.5 \times 1.35$ mm SMD package.
- Frequency stability down to ± 0.05 ppm; wide-temperature-range options up to $+105^{\circ}\text{C}$.
- 0.3 ppb/g acceleration sensitivity for compact precision timing.



iCONNEXION APPLICATION ENGINEERING

REQUIREMENTS & COMPONENT SELECTION

Translate system timing, synchronisation and environmental requirements into the right oscillator class and specification.

iCONNEXION ENGINEERING SUPPORT

Evaluate technical alternatives across frequency, stability, phase noise, package, power and availability.

DESIGN OPTIMISATION

Support power, thermal, PCB integration and environmental trade-offs during design-in.

LIFECYCLE & SUPPLY CONTINUITY

Support samples, sourcing, lifecycle visibility and continuity planning through production.



SILVERTEL & IEH

POWER & RUGGED INTERCONNECT SOLUTIONS



POWER OVER ETHERNET



Compact PoE PD and PSE modules simplify delivery of power and data over Ethernet. iConnexion supports module selection, power budgeting, thermal review and system integration.



Ag59800-LPB HIGH-POWER PoE++ PD MODULE

- IEEE 802.3bt Type 4 Class 8 PD
- Up to 89 W output
- 12 V / 24 V variants; DC/DC efficiency up to 95%



Ag6810 COMPACT PoE++ PSE MODULE

- IEEE 802.3bt Type 4 PSE with up to 95 W output
- Single-port Type 2 / 3 / 4 or dual Type 1 / 2 configurations
- Compact 28 × 18 × 5 mm SMT footprint.



Ag5700-LPB LOW-PROFILE PoE+ PD MODULE

- IEEE 802.3at Type 2 Class 4 PD
- 24 W continuous, up to 30 W peak output
- 12 V / 24 V variants; efficiency up to 89%



HYPERBOLOID INTERCONNECT TECHNOLOGY



IEH Hyperboloid contacts are engineered for low insertion force, low resistance, shock/vibration immunity and long mating life in demanding aerospace, defence and high-reliability systems.



HRM SERIES PCB HYPERBOLOID CONNECTORS

- 0.075 × 0.075 in spacing in 2- and 3-row configurations
- 10 to 206 contacts, depending on configuration
- Multiple PCB, flex, crimp and wire termination styles available



HMM HIGH-DENSITY PCB HYPERBOLOID CONNECTORS

- 0.075 × 0.075 in spacing in 4-, 6- and 8-row configurations.
- High-density arrangements extending to hundreds of contacts.
- Suitable where high contact density and dependable interconnection are required.



HBH HYBRID POWER / SIGNAL CONNECTORS

- Modular architecture combines power and signal contacts in one housing.
- Contact sizes from 0.016 in to 0.169 in.
- Low insertion force, high-current capability and shock/vibration immunity.



SiC POWER DEVICES

HIGH-VOLTAGE. FAST SWITCHING.
HIGH-TEMPERATURE CAPABILITY.

DACO's SiC MOSFET portfolio spans discrete and module solutions for high-voltage, high-frequency power conversion. iConnexion supports device and package selection, thermal considerations, samples and design-in evaluation for demanding power architectures.



WIDE VOLTAGE RANGE Discrete SiC MOSFET portfolio from 650 V to 2000 V.	HIGH-TEMPERATURE CAPABILITY Selected discrete devices support junction temperatures from -55°C to +175°C.	FAST SWITCHING Low capacitance and low RDS(on) support efficient high-frequency conversion.	APPLICATION ENGINEERING Support for package, thermal, gate-drive and power-stage selection.
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OUR SiC MOSFET PRODUCT FAMILIES

650 V SiC MOSFET, TOLL-8

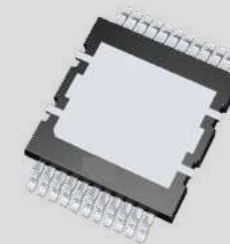
DAC010N065LY3



- 650 V; 25 mΩ RDS(on) typical
- 85 A continuous drain current at 25°C
- TOLL-8 package; suitable for high-frequency power conversion

1200 V SiC MOSFET, Q-DPAK

DAC020N120QD3



- 1200 V; 17 mΩ RDS(on) typical
- 125 A continuous drain current at 25°C
- Q-DPAK package for compact high-power switching stages

1700 V SiC MOSFET, TO-247-4L

DAC016N170ZY2



- 1700 V; 16 mΩ RDS(on) typical
- 138 A continuous drain current at 25°C
- -55°C to +175°C junction-temperature range

TARGET APPLICATION AREAS FOR DESIGN EVALUATION



MILITARY
VEHICLE
POWER



HIGH-
VOLTAGE
DC-DC & PFC



RADAR / EW
POWER SUPPLIES



ENERGY
STORAGE &
CHARGING



INVERTERS
& MOTOR
DRIVES



INPAQ & MATSUO

CAPACITOR AND RF SOLUTIONS



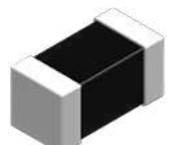
RF CONNECTIVITY. CIRCUIT PROTECTION. HIGH-RELIABILITY CAPACITORS.

INPAQ provides RF antenna and circuit-protection solutions for communications, navigation and embedded electronics. iConnexion supports product selection, specification review and system integration for demanding applications.



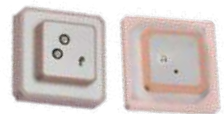
LOW-CAPACITANCE ESD SUPPRESSORS

- ESD suppressor families for sensitive signal interfaces.
- Low-capacitance options for RF and high-speed signal paths.
- Device selection should be matched to interface and protection requirements.



MULTILAYER VARISTORS

- Compact over-voltage protection for power and signal lines.
- Product families address communications, networking, industrial and automotive electronics.
- Multiple voltage and application options available.



GNSS & RF ANTENNA SOLUTIONS

- Portfolio includes GNSS and RF antenna solutions.
- Selection around frequency band, gain, efficiency, form factor and integration.
- Supports navigation, timing, communications and wireless platforms.



TANTALUM CAPACITORS & CIRCUIT PROTECTION

Matsuo provides tantalum capacitors and current-fuse protection devices for compact, high-reliability electronics. iConnexion supports component selection, qualification review and design-in requirements, including space-system applications.



267P SERIES — JAXA-CERTIFIED TANTALUM CAPACITORS

- High-reliability tantalum series for space-system equipment.
- JAXA CWS11-certified.
- 4 to 50 VDC; 0.1 to 100 μ F



CONDUCTIVE-POLYMER TANTALUM CAPACITORS

- TCA / TCB families use conductive-polymer technology for ultra-low ESR.
- 2.5 to 10 VDC options across compact SMD case sizes.
- Suitable for high-frequency power-line filtering and compact power electronics.



CURRENT FUSES / CIRCUIT PROTECTION

- Surface-mount current-fuse families for compact electronic protection.
- High-reliability and AEC-Q200-qualified options are available in selected series.
- Select the appropriate rating and qualification to suit the programme requirements.

NITSUKO & SOSHIN

RF, PROTECTION & HIGH-RELIABILITY PASSIVES



FILM CAPACITORS FOR POWER ELECTRONICS

Nitsuko film capacitors support DC-link, filtering, smoothing and high-temperature power-electronics applications. iConnexion supports capacitance and voltage selection, thermal considerations and design-in requirements.



FPCS — COMPACT BOXED FILM CAPACITOR

- 630 VDC boxed / small-size series.
- 1.0 to 2.2 μ F capacitance range.
- Compact metallised-film construction for space-conscious power electronics.



FPT / FPT2 — HIGH-TEMPERATURE FILM CAPACITORS

- 630 VDC high-temperature film-capacitor families.
- -40°C to +105°C operating range, with +125°C derating conditions depending on the series and rating.
- Compact options for power-supply and harsh-temperature designs.



FPCL — POWER-ELECTRONICS FILM CAPACITORS

- Long-life, high-voltage, high-current metallised polypropylene construction.
- 630 to 1300 VDC; 1 to 65 μ F across the family.
- Designed for DC-link, DC filtering and smoothing applications.



RF / MICROWAVE & EMI SOLUTIONS

Soshin provides RF, microwave and EMI components for signal distribution, filtering and noise suppression. iConnexion supports frequency-band selection, component matching and system-integration review.



HMD SERIES — HYBRID COUPLERS

- Compact, broadband coupler families with high-power capability.
- Representative HMD devices cover multiple RF bands and coupling architectures.
- Designed for RF signal distribution and monitoring applications.



RF & IF FILTERS

- HMD / MDR / DBF / PMDR multilayer dielectric filter families.
- Low insertion loss with high out-of-band attenuation.
- Compact filtering for RF and IF signal chains.



EMI / NOISE-SUPPRESSION SOLUTIONS

- EMI filters for industrial, telecommunications and electronic equipment.
- Ring cores / cut cores for signal-line noise suppression.
- Surge-absorber and related noise-control solutions available.

Contact us

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